

FEATURES

- ◆For surface mounted applications
- ◆Glass Passivated Chip Junction
- ◆Fast reverse recovery time
- ◆Ideal for automated placement
- ◆Lead free in comply with EU RoHS 2011/65/EU directives



Pinning

1.Cathode	2.Anode
1	2
SOD-323FL	

MECHANICAL DATA

- ◆Case: SOD-323FL
- ◆Terminals: Solderable per MIL-STD-750, Method 2026
- ◆Approx. Weight: 4.5mg /0.00016oz

Marking Code

BAV19WSFL	A8
BAV20WSFL	T2
BAV21WSFL	T3

Absolute Maximum Ratings at 25 °C

Parameter		Symbols	BAV19WSFL	BAV20WSFL	BAV21WSFL	Units
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	120	200	250	V
Maximum RMS voltage		V_{RMS}	100	150	200	V
Continuous Forward Current		I_F	250			mA
Repetitive Peak Forward Current		I_{FRM}	625			mA
Non-reptitive Peak Forward Surge Current	at 1s	I_{FSM}	1			A
	at 1ms		3			
	at 1us		9			
Total Power Dissipation		P_{tot}	500			mW
Operating and Storage Temperature Range		T_j, T_{stg}	-55 ~ +150			°C

Characteristics at Ta = 25 °C

Parameter		Symbols	BAV19WSFL	BAV20WSFL	BAV21WSFL	Units
Reverse BreakdownVoltage at IR=100μA		V _{(BR)R}	120	200	250	V
Maximum Forward Voltage	at 100 mA	V _F	1.00			V
	at 200 mA		1.25			
Maximum DC Reverse Current at Rated DC Blocking Voltage	T _a =25°C	I _R	0.1			uA
	T _a =150°C		100			
Typical Junction Capacitance at V _R =4V, f=1MHz		C _j	5			pF
Maximum Reverse Recovery Time		T _{rr}	50			nS

Fig.1 Power Derating Curve

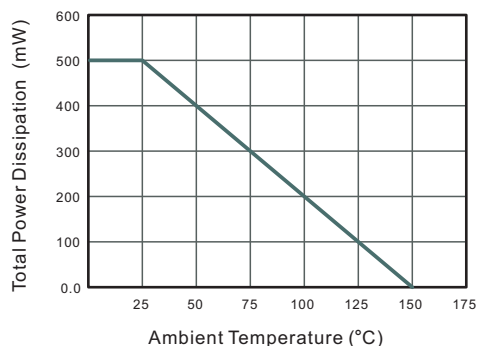


Fig.2 Typical Reverse Characteristics

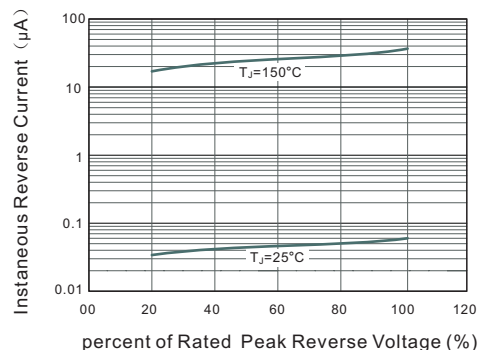


Fig.3 Typical Instaneous Forward Characteristics

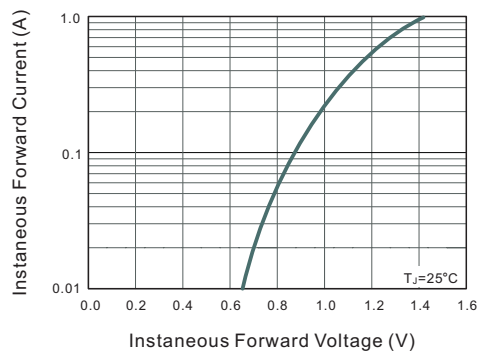
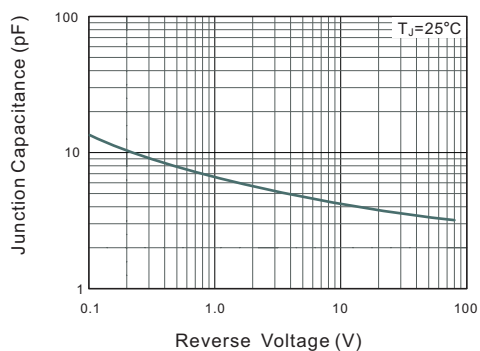


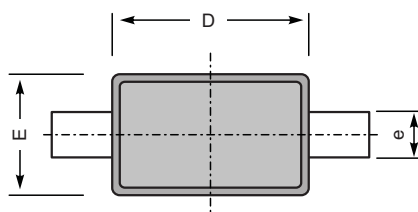
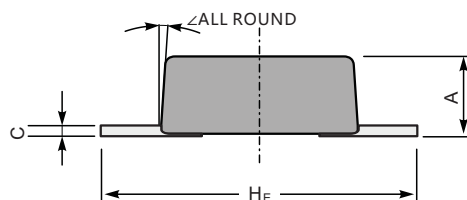
Fig.4 Typical Junction Capacitance



Package Outline

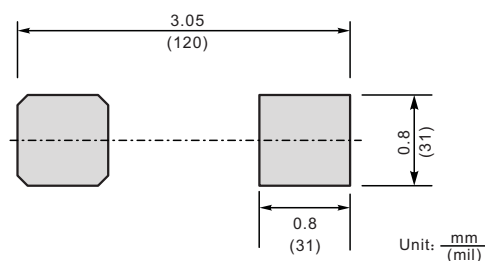
SOD-323FL

Plastic surface mounted package; 2 leads



UNIT		A	C	D	E	e	H _E	∠
mm	max	1.0	0.25	1.8	1.35	0.4	2.7	8°
	min	0.8	0.05	1.6	1.15	0.25	2.3	
mil	max	39	9.8	71	53	18	106	
	min	31	2.0	63	45	10	91	

The recommended mounting pad size



Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
SOD-323FL	Tape/Reel, 7" reel	3000	EIA-481-1